

# Material Declaration Report



Package Type:	SOT23-3
Pericom Package Code:	TA03 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	13.731
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	Oct,18.2011

## Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	8.440	J	Solid Epoxy Resin	Trade Secret	11.00	0.92840
			Phenol Resin	Trade Secret	11.00	0.92840
			Fused Silica	60676-86-0	60.00	5.06400
			Metal Hydro Oxide	Trade Secret	10.00	0.84400
			Carbon Black	1333-86-4	5.00	0.42200
			Crystalline Silica	14808-60-7	3.00	0.25320
LEAD FRAME	4.050		Cu	7440-50-8	90.54	3.66687
			Fe	7439-89-6	2.35	0.09518
			P	7723-14-0	0.08	0.00324
			Zn	7440-66-6	0.13	0.00527
			Pb	7439-92-1	0.30	0.01215
			Silver	7440-22-4	6.60	0.26730
TERMINATION PLATING	0.6820		Tin	7440-31-5	99.90	0.68132
			Impurity	Proprietary	0.10	0.00068
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.039		Silica	14808-60-7	46.25	0.01804
			Epoxy resin	Secret	46.25	0.01804
			固化剂	Secret	7.50	0.00293
GOLD WIRE	0.170		Au	7440-57-5	99.99	0.16998
			Other materials	Proprietary	0.01	0.00002

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

## 3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

## ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	<b>Declaration Statement:</b>	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
		<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td>&lt;1000ppm</td> <td>&lt;1000ppm</td> <td>&lt;1000ppm</td> <td>&lt;100ppm</td> <td>&lt;1000ppm</td> <td>&lt;1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE														
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm														
O	O	O	O	O	O														
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.  X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																			